

6872 Foundations of Electronics

Lecture 9: Field Effect Transistor (FET)

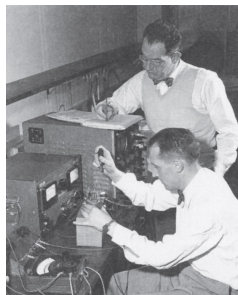
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Abstract

- ▶ JFET: Basic Construction and Operation
- ▶ MOSFET: Basic Construction and Operation
- ▶ Biasing Circuits
 - ▶ Fixed-Bias
 - ▶ Self-Bias
 - ▶ Voltage-Divider Bias



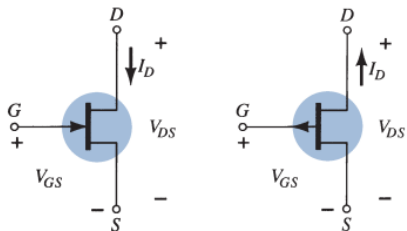
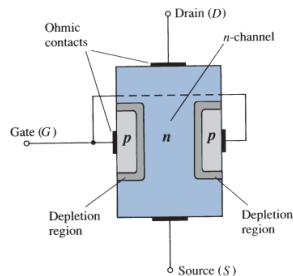
Ian M. Ross (front) and G. C. Dacey jointly developed an experimental procedure for measuring the characteristics of a field-effect transistor in 1955.

FET and BJT

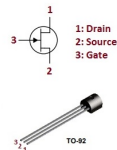
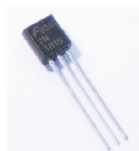
- ▶ Field-Effect Transistor (FET) is a three-terminal device with use similar to the BJT
- ▶ Primary differences between FET and BJT
 - ▶ BJT is a current-controlled device (controlled by I_B)
FET is a voltage-controlled device (controlled by V_{GS})
 - ▶ BJT is a bipolar device: conduction done by electrons and holes)
FET is a unipolar device: conduction done by either electrons (N-channel device) or holes (P-channel device)
- ▶ FET has a very high input impedance ($I_G \approx 0$)
- ▶ FETs are more temperature stable than BJTs
- ▶ FETs are usually smaller than BJTs, making them particularly useful in integrated-circuit (IC) chip
- ▶ Voltage gain for BJT amplifier is typically greater than for FET amplifiers
- ▶ FET types: Junction FET (JFET), and Metal-Oxide-Semiconductor FET (MOSFET) depletion and enhancement types

Junction FET Construction

- ▶ N-channel JFET (depicted) and P-channel JFET
- ▶ Channel (N-type) connected at each end to drain (D) and source (S) terminals
- ▶ Channel between embedded layers of P-type material
- ▶ P-type layers form gate (G) terminal
- ▶ Symbols



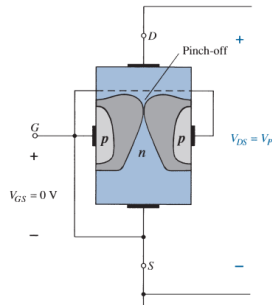
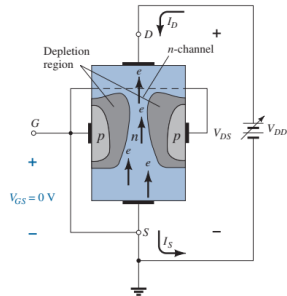
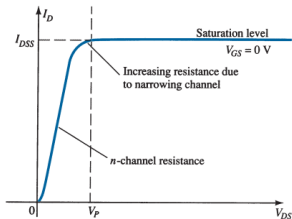
N-channel (left) and P-channel (right) FETs



Junction FET Operation

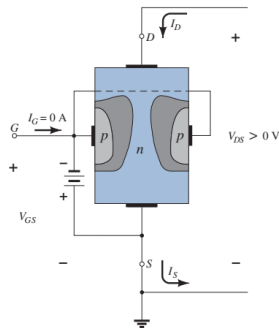
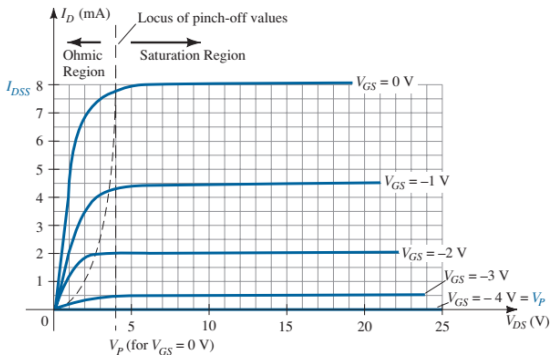
► $V_{GS} = 0, V_{DS} > 0$

- Junction PN is reverse biased and $I_G = 0$
- Current $I_D = I_S$ flows between drain and source
- Current is limited solely by the resistance of the N-channel
- Depletion region is wider closer to drain terminal because of higher positive voltage
- For $V_{DS} = V_P$, the two depletion zones would touch, a condition known as **pinch-off**
- With pinch-off, the channel current saturates at $I_D = I_{DSS}$ (for $V_{GS} = 0$)



Junction FET Operation

- ▶ $V_{GS} < 0$, $V_{DS} > 0$
 - ▶ Negative V_{GS} widens depletion region
 - ▶ Pinch-off (and saturation current) reached earlier
 - ▶ For each value of V_{GS} , there is a curve $V_{DS} \times I_D$
 - ▶ JFET characteristics includes **ohmic region** and **saturation region**
 - ▶ Note that for $V_{GS} < V_P$, $I_D = 0$



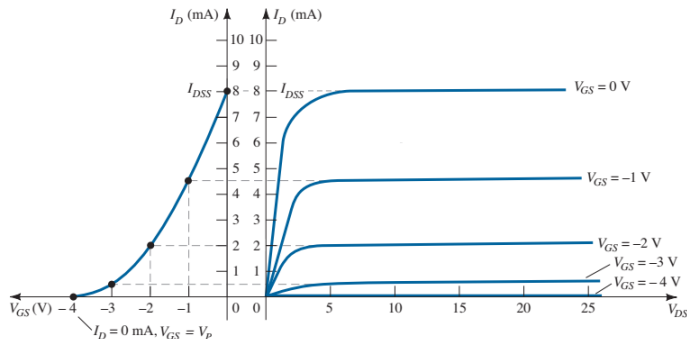
Assuming $I_{DSS} = 8\text{ mA}$ and $V_P = -4\text{ V}$

Junction FET Characteristics

- ▶ BJT has a linear relationship between the controlling current (I_B) and the output current I_C : $I_C = \beta I_B$
- ▶ For JFET, this relationship is not linear:

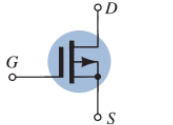
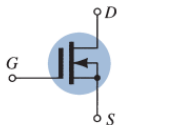
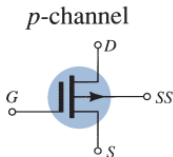
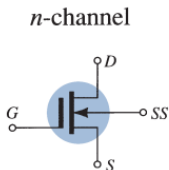
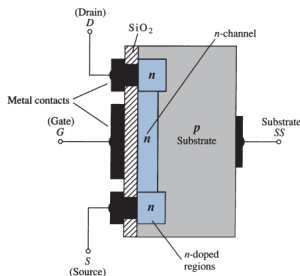
$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

I_{DSS} and V_P are given in datasheet



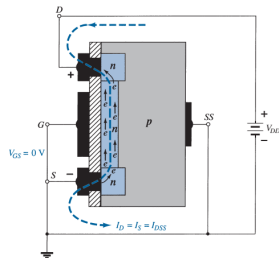
Depletion MOSFET Construction

- ▶ N-channel (depicted) and P-channel Depletion MOSFET
- ▶ Channel (N-type) connected at each end to drain (D) and source (S) terminals
- ▶ Gate is insulated from N-channel by a very thin silicon dioxide (SiO_2)
- ▶ Symbols



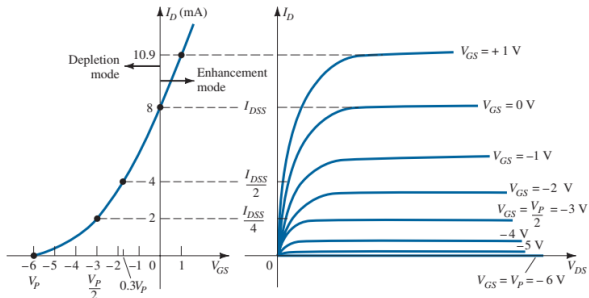
Depletion MOSFET Operation

- ▶ $V_{GS} = 0, V_{DS} > 0$
 - ▶ Current $I_D = I_S = I_{DSS}$ flows between drain and source
 - ▶ Current is only limited by channel resistance
- ▶ $V_{GS} < 0, V_{DS} > 0$
 - ▶ Channel electrons are repelled to P-type substrate, reducing the number of free electrons in the N-channel available for conduction
- ▶ $V_{GS} > 0, V_{DS} > 0$
 - ▶ Positive gate draws additional electrons from substrate



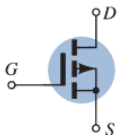
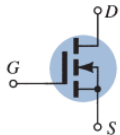
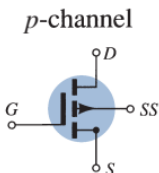
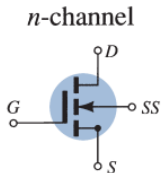
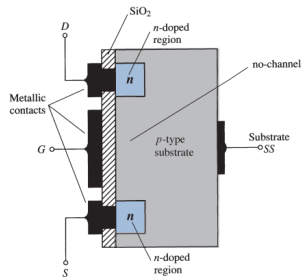
- ▶ Relationship $V_{GS} \times I_D$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$



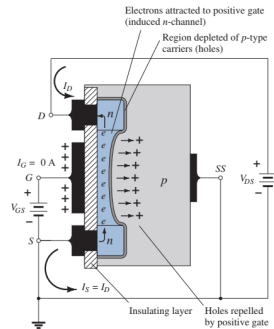
Enhancement MOSFET Construction

- ▶ N-channel (depicted) and P-channel Enhancement MOSFET
- ▶ Channel is absent as a constructed component
- ▶ Gate is insulated from N-channel by a very thin silicon dioxide (SiO_2)
- ▶ Symbols

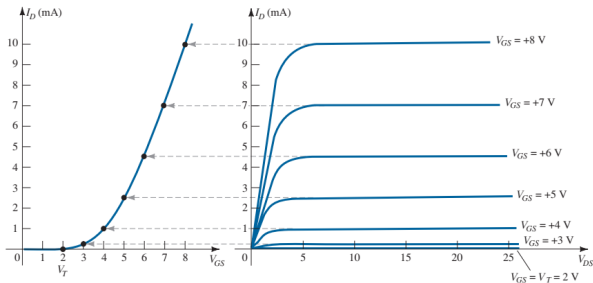


Enhancement MOSFET Operation

- ▶ $V_{GS} < V_T$, $V_{DS} > 0$
 - ▶ Channel absent and $I_D = I_S = 0$
- ▶ $V_{GS} > V_T$, $V_{DS} > 0$
 - ▶ Positive potential attracts electrons and a channel is formed
- ▶ Relationship $V_{GS} \times I_D$

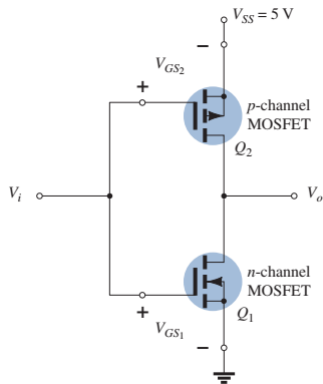
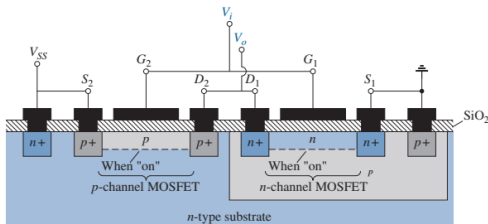


$$I_D = k (V_{GS} - V_T)^2 \quad \text{with } k = \frac{I_{D(on)}}{(V_{GS(on)} - V_T)^2}$$



Complementary MOSFET (CMOS)

- ▶ CMOS construction: P-channel and N-channel MOSFETs built on the same substrate, with similar (but opposite) characteristics
- ▶ Extensively used in logic circuit design
- ▶ Offers high input impedance, fast switching speeds, and lower operating power levels
- ▶ Example: NOT (inverter) gate



Biasing

- ▶ Biasing places transistor in its fixed operating point (Q-point)
- ▶ Important basic relationships for a transistor:

$$I_G \approx 0$$

$$I_D = I_S$$

- ▶ Relationship for JFET and depletion-type MOSFET:

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

- ▶ Relationship for enhancement-type MOSFET:

$$I_D = k (V_{GS} - V_T)^2$$

- ▶ Q-point can be determined using **analytical** or **graphical** approach

Biasing Circuits: Fixed-Bias

► Gate-Source loop

$$V_{GG} - I_G R_G + V_{GS} = 0$$

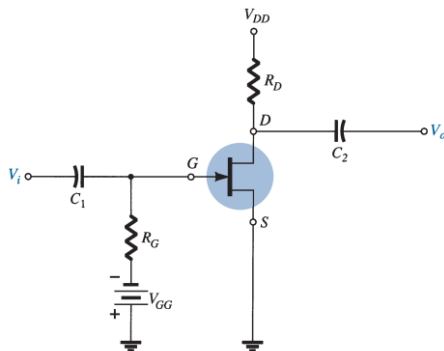
$$V_{GS} = -V_{GG}$$

► Drain-Source loop

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

$$V_{DD} - V_{DS} - I_D R_D$$

$$V_{DS} = V_{DD} - I_D R_D$$



Fixed-Bias Example

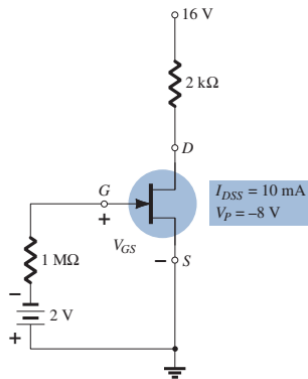
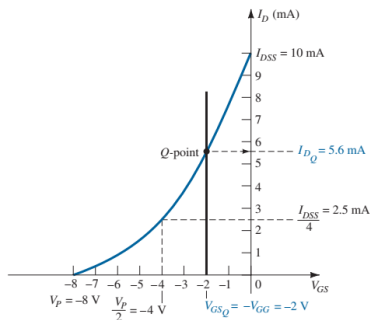
- Analytical approach:

$$V_{GS} = -V_{GG} = -2 \text{ V}$$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P}\right)^2 = 10\text{m} \left(1 - \frac{-2}{-8}\right)^2 = 5.63 \text{ mA}$$

$$V_{DS} = V_{DD} - I_D R_D = 16 - 5.63\text{m} \times 2\text{k} = 4.75 \text{ V}$$

- Graphical approach:



Biasing Circuits: Self-Bias

- ▶ Gate-Source loop

$$I_D R_S - I_G R_G + V_{GS} = 0$$

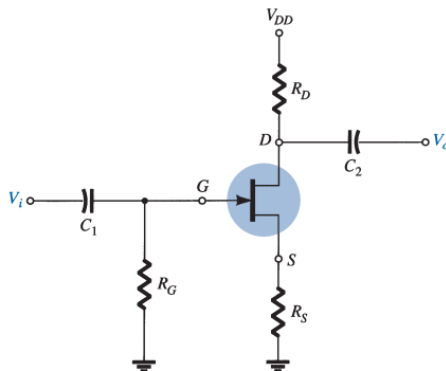
$$V_{GS} = -I_D R_S$$

- ▶ Drain-Source loop

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

$$V_{DD} - V_{DS} - I_D (R_D + R_S)$$

$$V_{DS} = V_{DD} - I_D (R_D + R_S)$$



Self-Bias Example

► Analytical approach:

$$V_{GS} = -I_D R_S = -1k I_D \leftarrow \text{load-line}$$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

$$= 8m \left(1 - \frac{-1k I_D}{-6} \right)^2 \rightarrow$$

$$\frac{2k}{9} I_D^2 - \frac{11}{3} I_D + 8m = 0 \rightarrow$$

$$I_D = 13.9 \text{ mA, or } I_D = 2.59 \text{ mA}$$

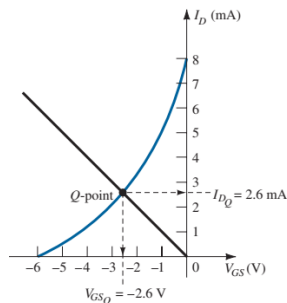
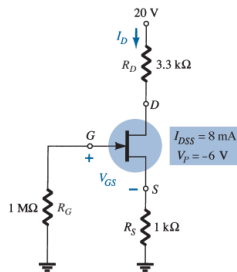
$$V_{GS} = -1k \times 2.59m = -2.59 \text{ V}$$

$$V_{DS} = V_{DD} - I_D (R_D + R_S)$$

$$= 20 - 2.59m(3.3k + 1k)$$

$$= 8.86 \text{ V}$$

► Graphical approach →



Biasing Circuits: Voltage-Divider Bias

► Gate-Source loop

$$V_G = \frac{R_2}{R_1 + R_2} V_{DD}$$

$$V_G - V_{GS} - I_D R_S = 0$$

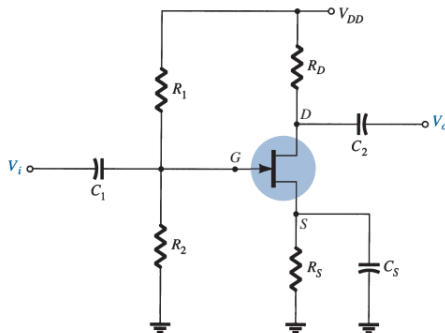
$$V_{GS} = V_G - I_D R_S$$

► Drain-Source loop

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

$$V_{DD} - V_{DS} - I_D (R_D + R_S) = 0$$

$$V_{DS} = V_{DD} - I_D (R_D + R_S)$$



Voltage-Divider Bias Example

► Analytical approach:

$$V_G = \frac{R_2}{R_1 + R_2} V_{DD} = \frac{270\text{k}}{2.1\text{M} + 270\text{k}} 16 = 1.82 \text{ V}$$

$$V_{GS} = V_G - I_D R_S = 1.82 - 1.5\text{k} I_D \leftarrow \text{load-line}$$

$$I_D = I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2$$

$$= 8\text{m} \left(1 - \frac{1.82 - 1.5\text{k} I_D}{-4} \right)^2 \rightarrow$$

$$1.125\text{k} I_D^2 - 9.734 I_D + 16.952\text{m} = 0 \rightarrow$$

$$I_D = 6.24 \text{ mA}, \text{ or } I_D = 2.42 \text{ mA}$$

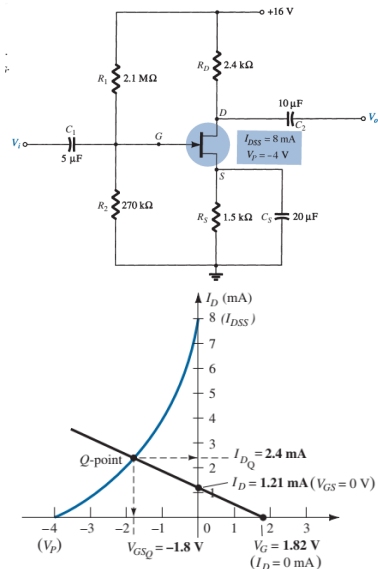
$$V_{GS} = 1.82 - 1.5\text{k} \times 2.42\text{m} = -1.81 \text{ V}$$

$$V_{DS} = V_{DD} - I_D (R_D + R_S)$$

$$= 16 - 2.42\text{m} (2.4\text{k} + 1.5\text{k})$$

$$= 6.56 \text{ V}$$

► Graphical approach →



Voltage-Divider Bias Example

► Graphical approach:

$$V_G = \frac{R_2}{R_1 + R_2} V_{DD} = \frac{18\text{M}}{22\text{M} + 18\text{M}} 40 = 18 \text{ V}$$

$$V_{GS} = V_G - I_D R_S = 18 - 820 I_D \leftarrow \text{load-line}$$

$$k = \frac{I_{D(on)}}{(V_{GS(on)} - V_T)^2}$$

$$= \frac{3\text{m}}{(10 - 5)^2} = 0.12 \text{ mA/V}^2$$

$$I_D = k (V_{GS} - V_T)^2 = 0.12\text{m} (V_{GS} - 5)^2$$

$$V_{GS} = 10 \text{ V} \rightarrow I_D = 3 \text{ mA}$$

$$V_{GS} = 15 \text{ V} \rightarrow I_D = 12 \text{ mA}$$

$$V_{GS} = 20 \text{ V} \rightarrow I_D = 27 \text{ mA}$$

